

therefrom that the permeability number has a maximum at a temperature of about 20° C. and a minimum at a temperature of about 75° C. At a temperature in a range of from 25° to 40° C. in which operating temperatures of technical apparatuses normally lie the temperature dependence shows a relatively steep slope. Even if one tries to actively stabilize the temperature of the rings 45 in this range by means of a temperature-adjusting unit, inevitable temperature variations nevertheless result in changes in the permeability number of the rings 45. According to the invention, the temperature of the rings 45 is thus adjusted to a nominal temperature which is in a temperature range in which there are only small temperature-dependent variations in the permeability number and which is preferably at an extremum of the temperature dependency of the permeability number, i.e., either to a temperature of about 20° or a temperature of about 75°.

[0037] To this end, a temperature-adjusting unit 49 schematically shown in FIG. 2 is provided. It comprises plural windings 51 of a conduit 53 through which a liquid flows, for example, water. The liquid flows through the conduit 53 in a closed circuit 55 which passes through a heating/cooling unit 57 in which the liquid flowing through the conduit 53 is brought to a temperature which is adjustable by a controller 61. The windings 51 of the conduit 53 abut with a heat contact 59 against a beam tube 63 which forms part of a vacuum chamber of the particle optics 11.

[0038] The beam deflector 25 is disposed within the beam tube 63 in the region in which the windings 51 are wound around the outside of the beam tube 63. This allows a heat exchange between the beam tube 63 and the deflector 25 to take place by thermal radiation transfer. By adjusting the temperature of the medium flowing through the windings 51 by means of the heating/cooling unit 57, it is thus possible to adjust the temperature of the ferrite rings 45 of the beam deflector 25 in a range about the nominal temperature. This adjustment is effected through a feed-back control which comprises a sensor 65 fixed to the stack of rings 43, 45 and read out by the controller 61. Accordingly, the controller 61 can compare an actual temperature of the rings 43, 45 with the nominal temperature thereof and accordingly influence the temperature of the medium in the windings 51 via the cooling/heating unit 57.

[0039] In the temperature-adjusting unit shown in FIG. 2, the ferrite rings 45 are adjusted to a nominal temperature of 20° C., since at this temperature the material used for the rings 45 shows a maximum of the permeability number (see FIG. 4). As an alternative thereto, it is possible to select as the nominal temperature a value about 75° C. at which the permeability number of the material used for the rings 45 has a minimum. It is evident from FIG. 4 that at this temperature the extremum (minimum) has a considerably flatter shape than the extremum (maximum) at the temperature of 20° C. The permeability number can thus be held more accurately around the extremum at the nominal temperature of 75° C. than at the nominal temperature of 20° C. On the other hand, at the minimum at the higher temperature of 75° C., the value of the permeability number is considerably lower than at the maximum at 20° C., so that the magnetic effect of the ferrite rings 45 is correspondingly reduced at this temperature.

[0040] The beam deflector 25 further comprises sector electrodes 67 which are disposed radially within the rings

43, 45. They provide an additional electric deflecting field for the beam traversing the deflector 25, which deflecting field is superimposed with the magnetic field provided by the beam conductors 47. Accordingly, the deflectors 25, 27 can be operated as a Wien filter, and deflection angles β provided by the deflectors 25, 27 can thus be adjusted with additional degrees of freedom. In particular, the magnetic fields and the electric fields provided for the deflection can be adjusted such that substantially the same deflection angles β result for both the primary electrons and the secondary electrons.

[0041] The beam conductors 47 are energized such that the magnetic flux in the ferrite rings 45 is well below a saturation value, such that changes in the magnetic field have a substantially linear dependency from variations of an energizing current. For example, a maximum flux induced in the ferrite rings 45 may be below 25% of a saturation flux therein, or in particular below 15% or even below 10%. Further, the energizing current may be an AC current such that an orientation of the magnetic flux carried by the ferrite rings changes from time to time or periodically.

[0042] A variant of the embodiment described with reference to FIGS. 1 to 4 will now be described. Components which correspond in function or structure to components of FIGS. 1 to 4 are designated by the same reference numbers, however, supplemented by an additional letter for the purpose of distinction. Reference is made to the entire above description.

[0043] FIG. 5 schematically shows a lithography system 71 used for transferring a pattern stored in a memory 73 of a controller 29a onto a particle-sensitive layer or resist with which a surface 3a of a semiconductor wafer 5a is coated in a lithography process for manufacturing miniaturized semiconductor structures.

[0044] The transfer of the pattern is effected by means of a writing electron beam 33a. It is generated by an electron source 35a which comprises a cathode plate 75 which has a tip 77 embossed therein. The tip 77 is disposed opposite to a bore of an aperture stop 39a which is biased in respect of the cathode plate 75 as anode. Furthermore, the tip 77 is disposed on an optical axis 17a of the lithography system 71 and is illuminated from above by a laser beam 78 generated by a semiconductor laser 79 and collimated by a collimating lens 81 into the tip 77. By controlling the laser 79 via the controller 29a, it is possible to rapidly switch the laser beam 78 on and off. The laser beam 78 supports a photon-assisted field emission in the region of the tip 77, as a result of which electrons are extracted from the tip 77 and accelerated through the aperture stop 39a to form the writing electron beam 33a which, after having passed through the aperture stop 39a, passes through a collimating lens 37a.

[0045] The collimating lens 37a further forms the writing electron beam 33a to a substantially parallel beam travelling along the optical axis 17a. This beam successively passes through two deflectors 25a and 27a concentrically disposed in respect of the optical axis 17a and then enters an objective 19a which finely focuses the same on the semiconductor surface 3a or object plane of the lithography system 71. The structure of the deflectors 25a and 27a is similar to that of the beam deflectors described with reference to FIGS. 2 and 3. Furthermore, a coil 83 likewise controlled by the controller 29a is disposed within the objective lens 19a, which